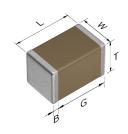
## 积层贴片陶瓷片式电容器

## C2012X5R1A156M125AB

RoHS Reach Halogen Free Pb Free

交货型号	C2012X5R1A156MT****
用途	一般等级
特点	General 一般(~75V)
系列	C2012 [EIA 0805]
状态	量产体制



尺寸			
长度(L)	$2.00 \text{mm} \pm 0.20 \text{mm}$		
宽度(W)	1.25mm ±0.20mm		
厚度(T)	1.25mm ±0.20mm		
端子宽度(B)	0.20mm Min.		
端子间隔(G)	0.50mm Min.		
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)		
1世存产益和问(FA)	0.90mm to 1.20mm(Reflow Soldering)		
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)		
1世存/杆鉱/仰/问 (LD)	0.70mm to 0.90mm(Reflow Soldering)		
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)		
1世45/开血41/四(110)	0.90mm to 1.20mm(Reflow Soldering)		

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电容	15 μ F ±20%
额定电压	10VDC
温度特性	$X5R(\pm 15\%)$
耗散因数(Max.)	10%
绝缘电阻 (Min.)	6ΜΩ

	其他	
焊接方法	流体	
<b>汗</b> 按刀莅	回流	
AEC-Q200	NO	
包装形式	塑封编带(180mm卷筒)	
包装个数	2000pcs	

<sup>!</sup> Images are for reference only and show exemplary products.

<sup>!</sup> This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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特性图表(这是参考数据,并不保证产品的特性。)

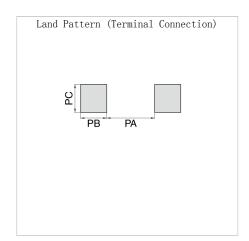
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## Associated Images



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